



**NSAI**  
Standards

Irish Standard  
I.S. EN 60068-2-20:2008

Environmental testing -- Part 2-20:  
Tests - Test T: Test methods for  
solderability and resistance to soldering  
heat of devices with leads (IEC 60068-2  
-20:2008 (EQV))

## I.S. EN 60068-2-20:2008

*Incorporating amendments/corrigenda issued since publication:*

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Údarás um Chaighdeáin Náisiúnta na hÉireann			

English version

**Environmental testing -  
Part 2-20: Tests -  
Test T: Test methods for solderability and resistance  
to soldering heat of devices with leads  
(IEC 60068-2-20:2008)**

Essais d'environnement -  
Partie 2-20: Essais -  
Essai T: Méthodes d'essai  
pour la brasabilité et la résistance  
à la chaleur de brasage  
des dispositifs plombés  
(CEI 60068-2-20:2008)

Umgebungseinflüsse -  
Teil 2-20: Prüfungen -  
Prüfung T: Prüfverfahren für die Lötbarkeit  
und Lötwärmebeständigkeit  
von Bauelementen mit herausgeführten  
Anschlüssen  
(IEC 60068-2-20:2008)

This European Standard was approved by CENELEC on 2008-08-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

**CENELEC**

European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Central Secretariat: rue de Stassart 35, B - 1050 Brussels**

## I.S. EN 60068-2-20:2008

EN 60068-2-20:2008

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### Foreword

The text of document 91/764/FDIS, future edition 5 of IEC 60068-2-20, prepared by IEC TC 91, Electronics assembly technology, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60068-2-20 on 2008-08-01.

This European Standard supersedes HD 323.2.20 S3:1988.

The major technical changes with regard to HD 323.2.20 S3:1988 are the following:

- the solder globule test is deleted;
- test conditions and requirements for lead-free solders are added.

The following dates were fixed:

- latest date by which the EN has to be implemented  
at national level by publication of an identical  
national standard or by endorsement (dop) 2009-05-01
- latest date by which the national standards conflicting  
with the EN have to be withdrawn (dow) 2011-08-01

Annex ZA has been added by CENELEC.

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### Endorsement notice

The text of the International Standard IEC 60068-2-20:2008 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-54	NOTE Harmonized as EN 60068-2-54:2006 (not modified).
IEC 60068-2-58	NOTE Harmonized as EN 60068-2-58:2004 (not modified).
IEC 60068-2-69	NOTE Harmonized as EN 60068-2-69:2007 (not modified).
IEC 61190-1-3	NOTE Harmonized as EN 61190-1-3:2007 (not modified).

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	- <sup>1)</sup>	Environmental testing - Part 1: General and guidance	EN 60068-1	1994 <sup>2)</sup>
IEC 60068-2-2	- <sup>1)</sup>	Environmental testing - Part 2-2: Tests - Test B: Dry heat	EN 60068-2-2	2007 <sup>2)</sup>
IEC 60068-2-66	- <sup>1)</sup>	Environmental testing - Part 2-66: Test methods - Test Cx: Damp heat, steady state (unsaturated pressurized vapour)	EN 60068-2-66	1994 <sup>2)</sup>
IEC 60068-2-78	- <sup>1)</sup>	Environmental testing - Part 2-78: Tests - Test Cab: Damp heat, steady state	EN 60068-2-78	2001 <sup>2)</sup>
IEC 60194	- <sup>1)</sup>	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	2006 <sup>2)</sup>
IEC 61191-3	- <sup>1)</sup>	Printed board assemblies - Part 3: Sectional specification - Requirements for through-hole mount soldered assemblies	EN 61191-3	1998 <sup>2)</sup>
IEC 61191-4	- <sup>1)</sup>	Printed board assemblies - Part 4: Sectional specification - Requirements for terminal soldered assemblies	EN 61191-4	1998 <sup>2)</sup>

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<sup>1)</sup> Undated reference.

<sup>2)</sup> Valid edition at date of issue.



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